HT7000 Thermal Conductive Gap Filler

BENEFITS AND FEATURES

- Easily dispensable and reworkable
- High thermal conductivity and low thermal impedance
- High compressibility for low stress applications
- No pump out and cracking risk
- Proven long term reliability

TYPICAL APPLICATIONS

- Telecommunications
- Consumer Electronics
- Automotive electronics
- Memory & power modules

OVERVIEW

Honeywell HT7000 is one-part, dispensable thermal gap filler with highly thermal conductivity. This material is formulated to balance the dispense rate, long term reliability and reworkable. With its high compressibility, it is designed to minimize thermal resistance at interfaces and maintain excellent performance through reliability testing.

STORAGE & USE

- Shelf life 12 months at 0-35°C, ≤65% RH

Reliability Test (JESD22-A104C)

Thermal Cycling –B (1000cycles)

Property	HT7000	Test Method
Feature	Silicone-based	-
	Pre-cured	-
Color	Red	Visual
Thermal Conductivity (W/m·K)	7.0	ASTM D5470
Thermal Impedance (°C·In^2/W) (1mm@10psi, Typical Value)	0.21	ASTM D5470
Dispense Rate (g/min)	18	90psi, 30cc EFD syringe
Density(g/cm^3)	3.50	ASTM D792
Minimum BLT (μm)	190	HON Internal
Volatile Content (TML%)	<0.05	HON Internal
Volatile Content (CVCM%)	<0.02	HON Internal
Dielectric Strength (KV/mm)	7	ASTM D149
Flammability Rating	V-0(Equivalent)	UL 94
Operating Temperature (°C)	-40~150	HON Internal

*Typical property data values should not be used as specifications

Honeywell Electronic Materials

USA: 1-509-252-2102
China: 400-840-2233
Germany: 49-5137-999-9199
Japan: 81-3-6730-7092
Korea: 82-2-3483-5076
Singapore: 65-6580-3593

DS.0318Rev3